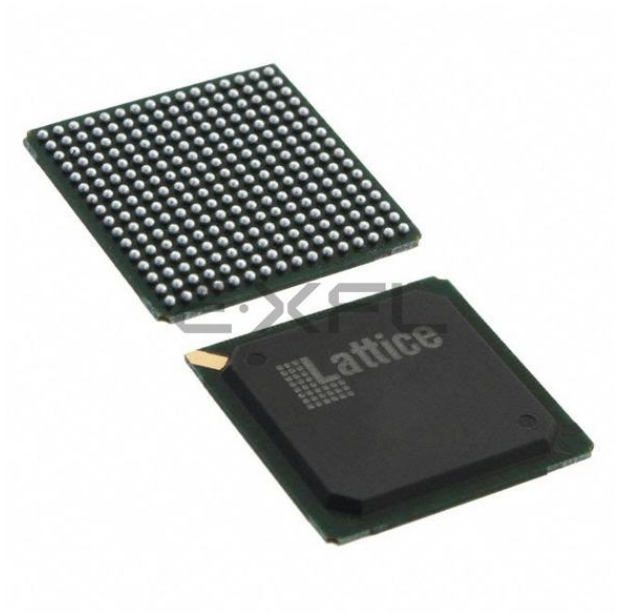
Lattice Semiconductor Corporation - LFE2-6SE-5F256I Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	750
Number of Logic Elements/Cells	6000
Total RAM Bits	56320
Number of I/O	190
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-6se-5f256i

Figure 2-1. Simplified Block Diagram, ECP2-6 Device (Top Level)

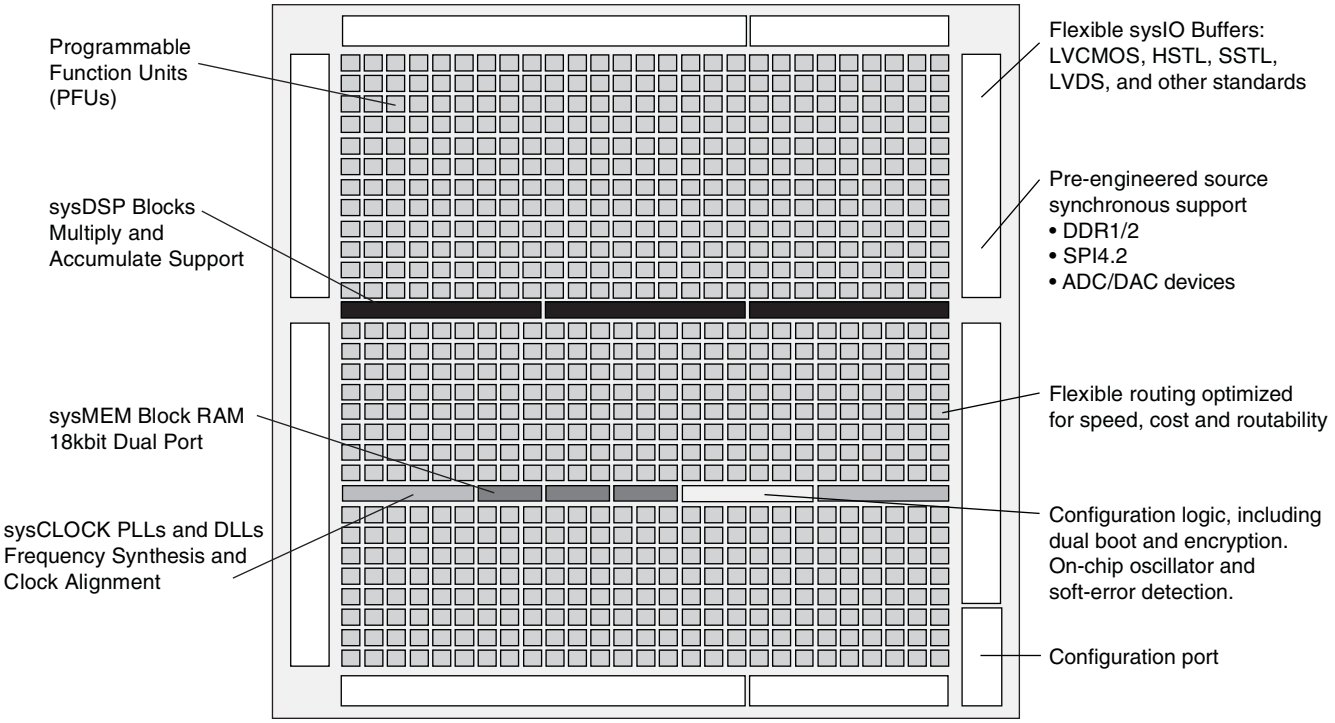
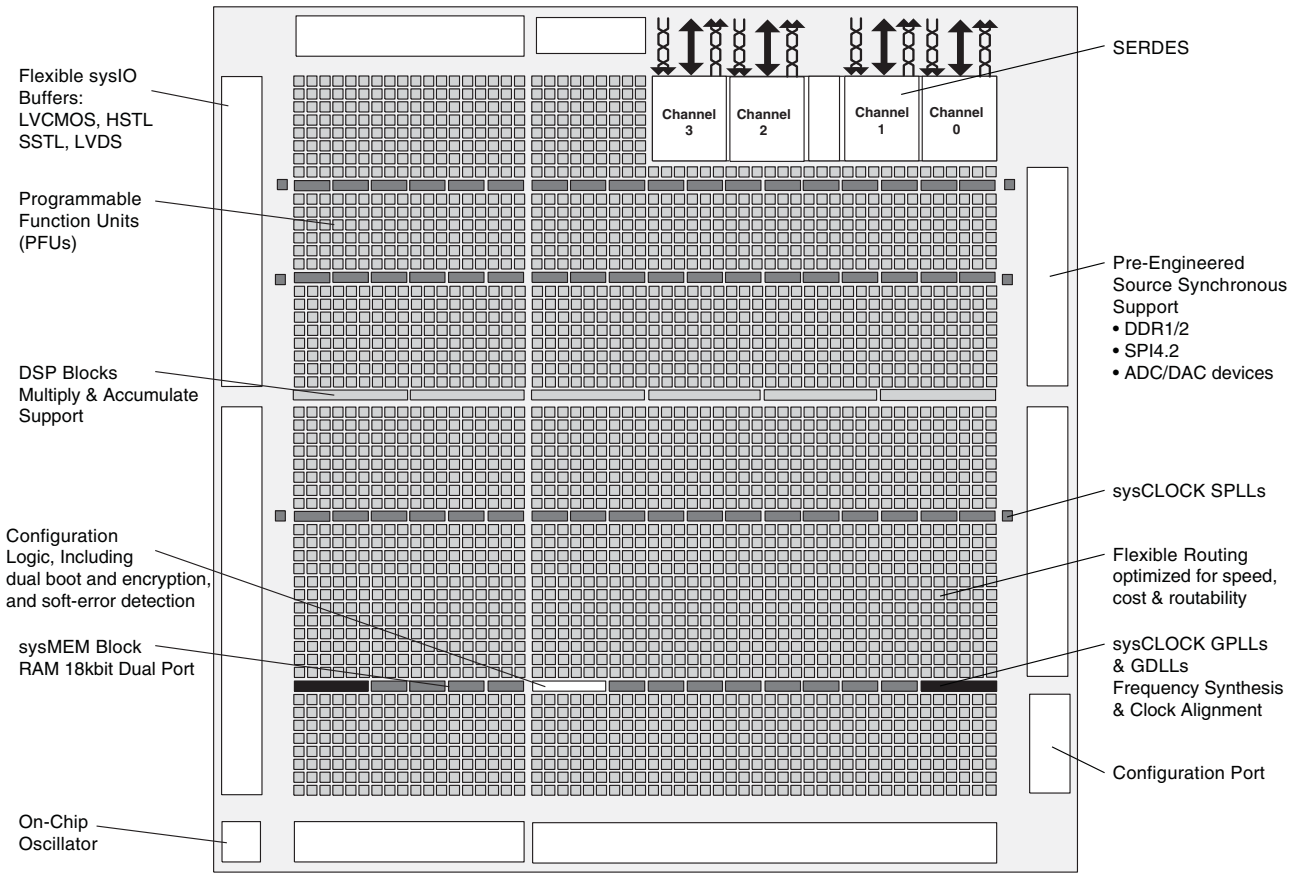


Figure 2-2. Simplified Block Diagram, ECP2M20 Device (Top Level)



IPexpress™

The user can access the sysDSP block via the IPexpress tool, which provides the option to configure each DSP module (or group of modules) or by direct HDL instantiation. In addition, Lattice has partnered with The MathWorks® to support instantiation in the Simulink® tool, a graphical simulation environment. Simulink works with Diamond to dramatically shorten the DSP design cycle in Lattice FPGAs.

Optimized DSP Functions

Lattice provides a library of optimized DSP IP functions. Some of the IP cores planned for the LatticeECP2/M DSP include the Bit Correlator, Fast Fourier Transform, Finite Impulse Response (FIR) Filter, Reed-Solomon Encoder/Decoder, Turbo Encoder/Decoder and Convolutional Encoder/Decoder. Please contact Lattice to obtain the latest list of available DSP IP cores.

Resources Available in the LatticeECP2/M Family

Table 2-9 shows the maximum number of multipliers for each member of the LatticeECP2/M family. Table 2-10 shows the maximum available EBR RAM Blocks in each LatticeECP2/M device. EBR blocks, together with Distributed RAM can be used to store variables locally for fast DSP operations.

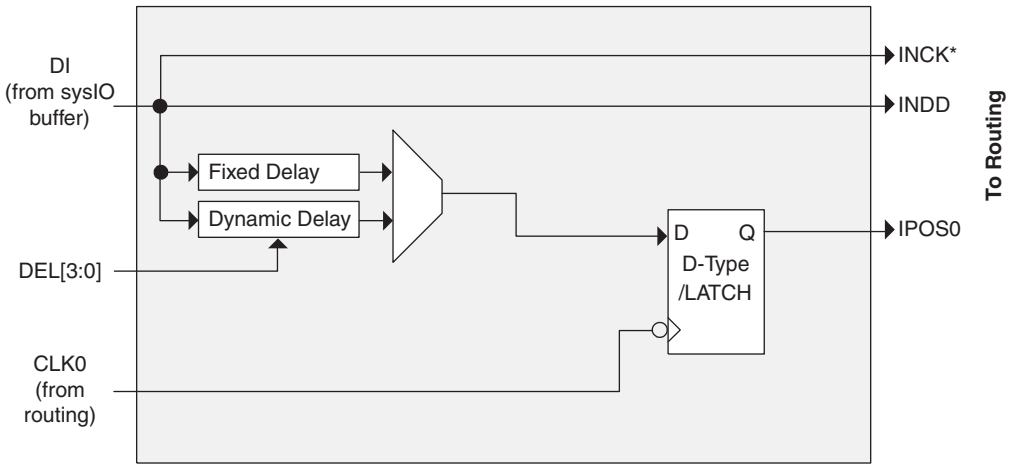
Table 2-9. Maximum Number of DSP Blocks in the LatticeECP2/M Family

Device	DSP Block	9x9 Multiplier	18x18 Multiplier	36x36 Multiplier
ECP2-6	3	24	12	3
ECP2-12	6	48	24	6
ECP2-20	7	56	28	7
ECP2-35	8	64	32	8
ECP2-50	18	144	72	18
ECP2-70	22	176	88	22
ECP2M20	6	48	24	6
ECP2M35	8	64	32	8
ECP2M50	22	176	88	22
ECP2M70	24	192	96	24
ECP2M100	42	336	168	42

Table 2-10. Embedded SRAM in the LatticeECP2/M Family

Device	EBR SRAM Block	Total EBR SRAM (Kbits)
ECP2-6	3	55
ECP2-12	12	221
ECP2-20	15	277
ECP2-35	18	332
ECP2-50	21	387
ECP2-70	60	1106
ECP2M20	66	1217
ECP2M35	114	2101
ECP2M50	225	4147
ECP2M70	246	4534
ECP2M100	288	5308

Figure 2-30. Input Register Block Top Edge



Note: Simplified version does not show CE and SET/RESET details.
*On selected blocks.

Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the sysI/O buffers. The blocks on the PIOs on the left, right and bottom contain a register for SDR operation that is combined with an additional latch for DDR operation. Figure 2-31 shows the diagram of the Output Register Block for PIOs on the left, right and the bottom edges. Figure 2-32 shows the diagram of the Output Register Block for PIOs on the top edge of the device.

In SDR mode, ONEG0 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured as a D-type or latch. In DDR mode, ONEG0 and OPOS0 are fed into registers on the positive edge of the clock. Then at the next clock cycle this registered OPOS0 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

By combining the output blocks of the complementary PIOs and sharing some registers from input blocks, a gearbox function can be implemented, that takes four data streams: ONEG0A, ONEG1A, ONEG1B and ONEG1B. Figure 2-32 shows the diagram using this gearbox function. For more information about this topic, please see information regarding additional documentation at the end of this data sheet.

DQSXFER

LatticeECP2/M devices provide a DQSXFER signal to the output buffer to assist it in data transfer to DDR memories that require DQS strobe be shifted 90°. This shifted DQS strobe is generated by the DQSDEL block. The DQSXFER signal runs the span of the data bus.

sysI/O Buffer

Each I/O is associated with a flexible buffer referred to as a sysI/O buffer. These buffers are arranged around the periphery of the device in groups referred to as banks. The sysI/O buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

sysI/O Buffer Banks

LatticeECP2/M devices have nine sysI/O buffer banks: eight banks for user I/Os arranged two per side. The ninth sysI/O buffer bank (Bank 8) is located adjacent to Bank 3 and has dedicated/shared I/Os for configuration. When a shared pin is not used for configuration it is available as a user I/O. Each bank is capable of supporting multiple I/O standards. Each sysI/O bank has its own I/O supply voltage (V_{CCIO}). In addition, each bank, except Bank 8, has voltage references, V_{REF1} and V_{REF2}, which allow it to be completely independent from the others. Bank 8 shares two voltage references, V_{REF1} and V_{REF2}, with Bank 3. Figure 2-37 shows the nine banks and their associated supplies.

In LatticeECP2/M devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS and PCI) are powered using V_{CCIO}. LVTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as fixed threshold inputs independent of V_{CCIO}.

Each bank can support up to two separate V_{REF} voltages, V_{REF1} and V_{REF2}, that set the threshold for the referenced input buffers. Some dedicated I/O pins in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

RSDS

The LatticeECP2/M devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Signaling)

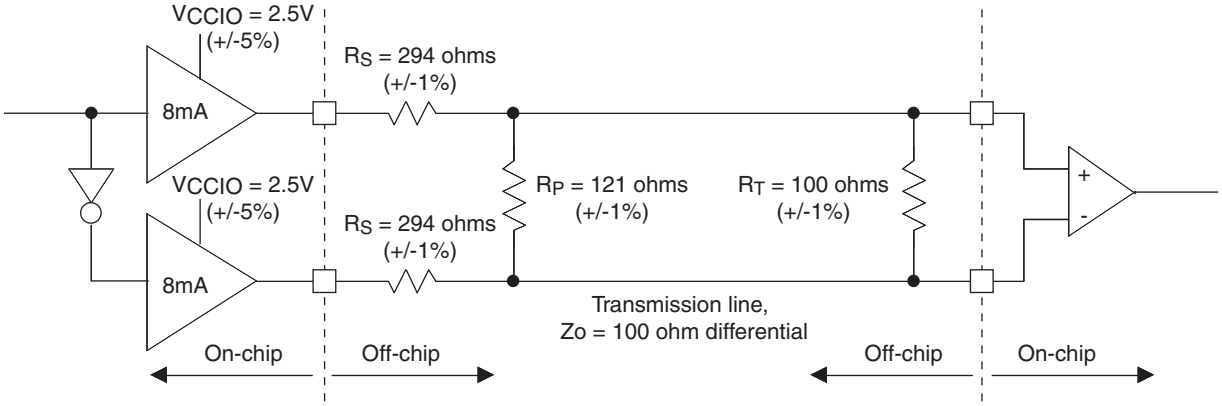


Table 3-5. RSDS DC Conditions[1]

Over Recommended Operating Conditions

Parameter	Description	Typical	Units
V_{CCIO}	Output Driver Supply (+/-5%)	2.50	V
Z_{OUT}	Driver Impedance	20	Ω
R_S	Driver Series Resistor (+/-1%)	294	Ω
R_P	Driver Parallel Resistor (+/-1%)	121	Ω
R_T	Receiver Termination (+/-1%)	100	Ω
V_{OH}	Output High Voltage	1.35	V
V_{OL}	Output Low Voltage	1.15	V
V_{OD}	Output Differential Voltage	0.20	V
V_{CM}	Output Common Mode Voltage	1.25	V
Z_{BACK}	Back Impedance	101.5	Ω
I_{DC}	DC Output Current	3.66	mA

1. For input buffer, see LVDS table.

LatticeECP2/M External Switching Characteristics[9] (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{DIBSPI}	Data Invalid Before Clock (Transmit)	ECP2-20	—	280	—	280	—	280	ps
		ECP2-35	—	280	—	280	—	280	ps
		ECP2-50	—	280	—	280	—	280	ps
		ECP2-70	—	280	—	280	—	280	ps
		ECP2M20	—	230	—	230	—	230	ps
		ECP2M35	—	230	—	230	—	230	ps
		ECP2M50	—	230	—	230	—	230	ps
		ECP2M70	—	230	—	230	—	230	ps
		ECP2M100	—	230	—	230	—	230	ps
XGMII I/O Pin Parameters (312 Mbps)[5]									
$t_{SUXGMII}$	Data Setup Before Read Clock	ECP2/M	480	—	480	—	480	—	ps
t_{HXGMII}	Data Hold After Read Clock	ECP2/M	480	—	480	—	480	—	ps
$t_{DVBCKXGMII}$	Data Valid Before Clock	ECP2/M	960	—	960	—	960	—	ps
$t_{DVACKXGMII}$	Data Valid After Clock	ECP2/M	960	—	960	—	960	—	ps
Primary									
f_{MAX_PRI}[7]	Frequency for Primary Clock Tree	ECP2/M	—	420	—	357	—	311	MHz
t_{W_PRI}	Clock Pulse Width for Primary Clock	ECP2/M	0.95	—	1.19	—	2.00	—	ns
t_{SKEW_PRI}	Primary Clock Skew Within a Bank	ECP2/M	—	300	—	360	—	420	ps
Edge Clock									
f_{MAX_EDGE}[7]	Frequency for Edge Clock	ECP2/M	—	420	—	357	—	311	MHz
t_{W_EDGE}	Clock Pulse Width for Edge Clock	ECP2/M	0.95	—	1.19	—	2.00	—	ns
t_{SKEW_EDGE}	Edge Clock Skew Within an Edge of the Device	ECP2/M	—	300	—	360	—	420	ps

1. General timing numbers based on LVCMOS 2.5, 12mA, 0pf load.
2. DDR timing numbers based on SSTL25 for BGA packages only.
3. DDR2 timing numbers based on SSTL18 for BGA packages only.
4. SPI4.2 and SFI4 timing numbers based on LVDS25 for BGA packages only.
5. XGMII timing numbers based on HSTL class I. A corresponding left/right dedicated clock buffer is used when using the SPI4.2 interface to the left or right edge of the device. For SPI4.2 mode, the software tool will help in selecting the appropriate clock buffer.
6. IP will be used to support DDR and DDR2 memory data rates down to 95MHz. This approach uses a free-running clock and PFU register to sample the data instead of the hardwired DDR memory interface.
7. Using the LVDS I/O standard.
8. ECP2-6 and ECP2-12 do not support SPI4.2
9. The AC numbers do not apply to PCLK6 and PCLK7.
10. Applies to CLKOP only.
11. Please refer to TN1159, LatticeECP2/M Pin Assignment Recommendations for best performance.

LatticeECP2/M Family Timing Adders[1, 2, 3] (Continued)

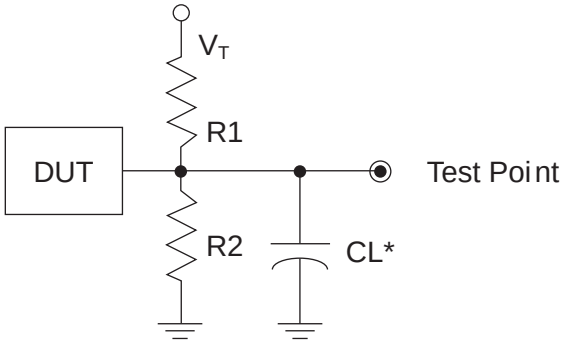
Over Recommended Operating Conditions

Buffer Type	Description	-7	-6	-5	Units
HSTL15_I	HSTL_15 class I 4mA drive	-0.22	-0.25	-0.27	ns
HSTL15D_I	Differential HSTL 15 class I 4mA drive	-0.22	-0.25	-0.27	ns
SSTL33_I	SSTL_3 class I	-0.12	-0.15	-0.18	ns
SSTL33_II	SSTL_3 class II	-0.20	-0.23	-0.27	ns
SSTL33D_I	Differential SSTL_3 class I	-0.12	-0.15	-0.18	ns
SSTL33D_II	Differential SSTL_3 class II	-0.20	-0.23	-0.27	ns
SSTL25_I	SSTL_2 class I 8mA drive	-0.16	-0.19	-0.22	ns
SSTL25_II	SSTL_2 class II 16mA drive	-0.19	-0.22	-0.25	ns
SSTL25D_I	Differential SSTL_2 class I 8mA drive	-0.16	-0.19	-0.22	ns
SSTL25D_II	Differential SSTL_2 class II 16mA drive	-0.19	-0.22	-0.25	ns
SSTL18_I	SSTL_1.8 class I	-0.14	-0.17	-0.20	ns
SSTL18_II	SSTL_1.8 class II 8mA drive	-0.20	-0.23	-0.25	ns
SSTL18D_I	Differential SSTL_1.8 class I	-0.14	-0.17	-0.20	ns
SSTL18D_II	Differential SSTL_1.8 class II 8mA drive	-0.20	-0.23	-0.25	ns
LVTTL33_4mA	LVTTL 4mA drive	0.52	0.60	0.68	ns
LVTTL33_8mA	LVTTL 8mA drive	0.06	0.08	0.09	ns
LVTTL33_12mA	LVTTL 12mA drive	0.04	0.04	0.05	ns
LVTTL33_16mA	LVTTL 16mA drive	0.03	0.02	0.02	ns
LVTTL33_20mA	LVTTL 20mA drive	-0.09	-0.09	-0.10	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive, fast slew rate	0.52	0.60	0.68	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive, fast slew rate	0.06	0.08	0.09	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive, fast slew rate	0.04	0.04	0.05	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive, fast slew rate	0.03	0.02	0.02	ns
LVCMOS33_20mA	LVCMOS 3.3 20mA drive, fast slew rate	-0.09	-0.09	-0.10	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive, fast slew rate	0.41	0.47	0.53	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive, fast slew rate	0.01	0.01	0.00	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive, fast slew rate	0.00	0.00	0.00	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive, fast slew rate	0.04	0.04	0.04	ns
LVCMOS25_20mA	LVCMOS 2.5 20mA drive, fast slew rate	-0.09	-0.10	-0.11	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive, fast slew rate	0.37	0.40	0.43	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive, fast slew rate	0.10	0.12	0.13	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive, fast slew rate	-0.02	-0.02	-0.02	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive, fast slew rate	-0.02	-0.03	-0.03	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive, fast slew rate	0.29	0.31	0.32	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive, fast slew rate	0.05	0.05	0.06	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive, fast slew rate	0.58	0.69	0.79	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive, fast slew rate	0.13	0.19	0.26	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive, slow slew rate	2.17	2.44	2.71	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive, slow slew rate	2.50	2.67	2.83	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive, slow slew rate	1.72	1.88	2.05	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive, slow slew rate	1.64	1.63	1.62	ns
LVCMOS33_20mA	LVCMOS 3.3 20mA drive, slow slew rate	1.33	1.36	1.39	ns

Switching Test Conditions

Figure 3-22 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-19.

Figure 3-22. Output Test Load, LVTTL and LVCMOS Standards



*CL Includes Test Fixture and Probe Capacitance

Table 3-19. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	R_2	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	∞	∞	0pF	LVCMOS 3.3 = 1.5V	—
				LVCMOS 2.5 = $V_{CCIO}/2$	—
				LVCMOS 1.8 = $V_{CCIO}/2$	—
				LVCMOS 1.5 = $V_{CCIO}/2$	—
				LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	∞	1MΩ		$V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> L)	1MΩ	∞		$V_{CCIO}/2$	V_{CCIO}
LVCMOS 2.5 I/O (H -> Z)	∞	100		V_{OH} - 0.10	—
LVCMOS 2.5 I/O (L -> Z)	100	∞		V_{OL} + 0.10	V_{CCIO}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions

Signal Name	I/O	Description
General Purpose		
P[Edge] [Row/Column Number*]_[A/B]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIC exists. When Edge is T (Top) or B (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B] indicates the PIO within the PIC to which the pad is connected. Some of these user-programmable pins are shared with special function pins. These pins, when not used as special purpose pins, can be programmed as I/Os for user logic. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration. See "Typical sysI/O I/O Behavior During Power-up" for more information about I/O behavior during power-up.
GSRN	I	Global RESET signal (active low). Any I/O pin can be GSRN.
NC	—	No connect.
GND	—	Ground. Dedicated pins.
V_{CC}	—	Power supply pins for core logic. Dedicated pins.
V_{CCAUX}	—	Auxiliary power supply pin. This dedicated pin powers all the differential and referenced input buffers.
V_{CCIOx}	—	Dedicated power supply pins for I/O bank x.
V_{CCPLL}	—	PLL supply pins. Should be tied to V_{CC} even when the corresponding PLL is unused.
V_{REF1_x}, V_{REF2_x}	—	Reference supply pins for I/O bank x. Pre-determined pins in each bank are assigned as V_{REF} inputs. When not used, they may be used as I/O pins.
XRES[4]	—	10K ohm +/-1% resistor must be connected between this pad and ground.
PLLCAP[4]	—	External capacitor connection for PLL.
PLL, DLL and Clock Functions (Used as user programmable I/O pins when not in use for PLL or clock pins)		
[LOC][num]_V_{CCPLL}	—	Power supply pin for PLL: LUM, LLM, RUM, RLM, num = row from center.
[LOC][num]_GPLL[T, C]_IN_A	I	General Purpose PLL (GPLL) input pads: LUM, LLM, RUM, RLM, num = row from center, T = true and C = complement, index A,B,C...at each side.
[LOC][num]_GPLL[T, C]_FB_A	I	Optional feedback GPLL input pads: LUM, LLM, RUM, RLM, num = row from center, T = true and C = complement, index A,B,C...at each side.
[LOC][num]_SPLL[T, C]_IN_A[5]	I	Secondary PLL (SPLL) input pads: LUM, LLM, RUM, RLM, num = row from center, T = true and C = complement, index A,B,C...at each side.
[LOC][num]_SPLL[T, C]_FB_A[5]	I	Optional feedback (SPLL) input pads: LUM, LLM, RUM, RLM, num = row from center, T = true and C = complement, index A,B,C...at each side.
[LOC][num]_DLL[T, C]_IN_A	I	DLL input pads: LUM, LLM, RUM, RLM, num = row from center, T = true and C = complement, index A,B,C...at each side.
[LOC][num]_DLL[T, C]_FB_A	I	Optional feedback (DLL) input pads: LUM, LLM, RUM, RLM, num = row from center, T = true and C = complement, index A,B,C...at each side.
PCLK[T, C]_[n:0]_[3:0]	I	Primary Clock pads, T = true and C = complement, n per side, indexed by bank and 0,1,2,3 within bank.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
B15	PT40B	1		C	PT49B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
A15	PT40A	1		T	PT49A	1		T
VCCIO	VCCIO1	1			VCCIO1	1		
A14	PT39A	1		T	PT48A	1		T
B14	PT39B	1		C	PT48B	1		C
D14	PT37B	1		C	PT46B	1		C
E14	PT36B	1		C	PT45B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
C13	PT37A	1		T	PT46A	1		T
F14	PT36A	1		T	PT45A	1		T
A13	PT35B	1		C	PT44B	1		C
E13	PT34B	1		C	PT43B	1		C
VCCIO	VCCIO1	1			VCCIO1	1		
B13	PT35A	1		T	PT44A	1		T
D13	PT34A	1		T	PT43A	1		T
E12	PT33B	1		C	PT42B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
D12	PT33A	1		T	PT42A	1		T
A12	PT31B	1		C	PT40B	1		C
B12	PT30B	1	PCLKC1_0	C	PT39B	1	PCLKC1_0	C
VCCIO	VCCIO1	1			VCCIO1	1		
A11	PT31A	1		T	PT40A	1		T
C12	PT30A	1	PCLKT1_0	T	PT39A	1	PCLKT1_0	T
F12	XRES	1			XRES	1		
B10	PT28B	0	PCLKC0_0	C	PT37B	0	PCLKC0_0	C
GNDIO	GNDIO0	-			GNDIO0	-		
B11	PT28A	0	PCLKT0_0	T	PT37A	0	PCLKT0_0	T
C11	PT26B	0		C	PT35B	0		C
A10	PT27B	0		C	PT36B	0		C
C10	PT26A	0		T	PT35A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
A9	PT27A	0		T	PT36A	0		T
A8	PT24B	0		C	PT33B	0		C
E11	PT25B	0		C	PT34B	0		C
A7	PT24A	0		T	PT33A	0		T
F11	PT25A	0		T	PT34A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
B8	PT23B	0		C	PT32B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
B9	PT23A	0		T	PT32A	0		T
C8	PT20B	0		C	PT29B	0		C
B7	PT21B	0		C	PT30B	0		C
D8	PT20A	0		T	PT29A	0		T

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
G17	PR13B	2	RDQ14	C	PR15B	2	RDQ16	C
F19	PR13A	2	RDQ14	T	PR15A	2	RDQ16	T
E20	PR12B	2	RDQ14	C (LVDS)*	PR14B	2	RDQ16	C (LVDS)*
D20	PR12A	2	RDQ14	T (LVDS)*	PR14A	2	RDQ16	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO	2		
F18	PR11B	2	RDQ14	C	PR13B	2	RDQ16	C
F16	PR11A	2	RDQ14	T	PR13A	2	RDQ16	T
C21	PR10B	2	RDQ14	C (LVDS)*	PR12B	2	RDQ16	C (LVDS)*
C22	PR10A	2	RDQ14	T (LVDS)*	PR12A	2	RDQ16	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO	2		
GNDIO	GNDIO2	-			GNDIO2	-		
D19	PR2B	2	VREF2_2/RDQ6	C (LVDS)*	PR2B	2	VREF2_2	C (LVDS)*
E19	PR2A	2	VREF1_2/RDQ6	T (LVDS)*	PR2A	2	VREF1_2	T (LVDS)*
B21	PT73B	1	VREF2_1	C	PT82B	1	VREF2_1	C
GNDIO	GNDIO1	-			GNDIO1	-		
B22	PT73A	1	VREF1_1	T	PT82A	1	VREF1_1	T
C20	PT72B	1		C	PT81B	1		C
C19	PT72A	1		T	PT81A	1		T
D18	PT71B	1		C	PT80B	1		C
VCCIO	VCCIO1	1			VCCIO	1		
E18	PT71A	1		T	PT80A	1		T
B20	PT70B	1		C	PT79B	1		C
A19	PT70A	1		T	PT79A	1		T
D17	PT69B	1		C	PT78B	1		C
C18	PT69A	1		T	PT78A	1		T
A21	PT68B	1		C	PT77B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
A20	PT68A	1		T	PT77A	1		T
A18	PT67B	1		C	PT76B	1		C
VCCIO	VCCIO1	1			VCCIO	1		
B18	PT67A	1		T	PT76A	1		T
G16	PT66B	1		C	PT75B	1		C
G15	PT66A	1		T	PT75A	1		T
D16	PT65B	1		C	PT74B	1		C
E16	PT65A	1		T	PT74A	1		T
GNDIO	GNDIO1	-			GNDIO1	-		
VCCIO	VCCIO1	1			VCCIO	1		
C17	PT55B	1		C	PT64B	1		C
GNDIO	GNDIO1	-			GNDIO1	-		
C16	PT55A	1		T	PT64A	1		T
B17	PT54B	1		C	PT63B	1		C
B16	PT54A	1		T	PT63A	1		T
A17	PT53B	1		C	PT62B	1		C
VCCIO	VCCIO1	1			VCCIO	1		
A16	PT53A	1		T	PT62A	1		T
C15	PT52B	1		C	PT61B	1		C

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
L2	NC	-			NC	-		
L1	NC	-			NC	-		
VCCIO	VCCIO7	7			VCCIO7	7		
M2	NC	-			NC	-		
M1	NC	-			NC	-		
N2	NC	-			NC	-		
GND	GNDIO7	-			GNDIO7	-		
M8	VCC	-			NC	-		
VCCIO	VCCIO7	7			VCCIO7	7		
GND	GNDIO7	-			GNDIO7	-		
N1	PL12A	7	LDQ16		PL18A	7	LDQ22	
L8	PL13A	7	LDQ16	T	PL19A	7	LDQ22	T
K8	PL13B	7	LDQ16	C	PL19B	7	LDQ22	C
VCCIO	VCCIO7	7			VCCIO7	7		
L6	PL14A	7	LDQ16	T (LVDS)*	PL20A	7	LDQ22	T (LVDS)*
K5	PL14B	7	LDQ16	C (LVDS)*	PL20B	7	LDQ22	C (LVDS)*
L7	PL15A	7	LDQ16	T	PL21A	7	LDQ22	T
L5	PL15B	7	LDQ16	C	PL21B	7	LDQ22	C
GND	GNDIO7	-			GNDIO7	-		
P1	PL16A	7	LDQS16	T (LVDS)*	PL22A	7	LDQS22	T (LVDS)*
P2	PL16B	7	LDQ16	C (LVDS)*	PL22B	7	LDQ22	C (LVDS)*
M6	PL17A	7	LDQ16	T	PL23A	7	LDQ22	T
VCCIO	VCCIO7	7			VCCIO7	7		
N8	PL17B	7	LDQ16	C	PL23B	7	LDQ22	C
R1	PL18A	7	LDQ16	T (LVDS)*	PL24A	7	LDQ22	T (LVDS)*
R2	PL18B	7	LDQ16	C (LVDS)*	PL24B	7	LDQ22	C (LVDS)*
M7	PL19A	7	PCLKT7_0/LDQ16	T	PL25A	7	PCLKT7_0/LDQ22	T
GND	GNDIO7	-			GNDIO7	-		
N9	PL19B	7	PCLKC7_0/LDQ16	C	PL25B	7	PCLKC7_0/LDQ22	C
M4	PL21A	6	PCLKT6_0/LDQ25	T (LVDS)*	PL27A	6	PCLKT6_0/LDQ31	T (LVDS)*
M5	PL21B	6	PCLKC6_0/LDQ25	C (LVDS)*	PL27B	6	PCLKC6_0/LDQ31	C (LVDS)*
N7	PL22A	6	VREF2_6/LDQ25	T	PL28A	6	VREF2_6/LDQ31	T
P9	PL22B	6	VREF1_6/LDQ25	C	PL28B	6	VREF1_6/LDQ31	C
N3	PL23A	6	LDQ25	T (LVDS)*	PL29A	6	LDQ31	T (LVDS)*
VCCIO	VCCIO6	6			VCCIO6	6		
N4	PL23B	6	LDQ25	C (LVDS)*	PL29B	6	LDQ31	C (LVDS)*
N5	PL24A	6	LDQ25	T	PL30A	6	LDQ31	T
P7	PL24B	6	LDQ25	C	PL30B	6	LDQ31	C
T1	NC	-			PL31A	6	LDQS31	T (LVDS)*
GND	GNDIO6	-			GNDIO6	-		
T2	NC	-			PL31B	6	LDQ31	C (LVDS)*
P8	NC	-			PL32A	6	LDQ31	T
P6	NC	-			PL32B	6	LDQ31	C
VCCIO	VCCIO6	6			VCCIO6	6		
P5	NC	-			PL33A	6	LDQ31	T (LVDS)*
P4	NC	-			PL33B	6	LDQ31	C (LVDS)*

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GND	GNDIO5	-			GNDIO5	-		
W10	PB20A	5	BDQ24	T	PB29A	5	BDQ33	T
Y10	PB20B	5	BDQ24	C	PB29B	5	BDQ33	C
W11	PB21A	5	BDQ24	T	PB30A	5	BDQ33	T
AA10	PB21B	5	BDQ24	C	PB30B	5	BDQ33	C
AC8	PB22A	5	BDQ24	T	PB31A	5	BDQ33	T
AD8	PB22B	5	BDQ24	C	PB31B	5	BDQ33	C
VCCIO	VCCIO5	5			VCCIO5	5		
AB8	PB23A	5	BDQ24	T	PB32A	5	BDQ33	T
AB10	PB23B	5	BDQ24	C	PB32B	5	BDQ33	C
GND	GNDIO5	-			GNDIO5	-		
AE6	PB24A	5	BDQS24	T	PB33A	5	BDQS33	T
AF6	PB24B	5	BDQ24	C	PB33B	5	BDQ33	C
AA11	PB25A	5	BDQ24	T	PB34A	5	BDQ33	T
AC9	PB25B	5	BDQ24	C	PB34B	5	BDQ33	C
AB9	PB26A	5	BDQ24	T	PB35A	5	BDQ33	T
AD9	PB26B	5	BDQ24	C	PB35B	5	BDQ33	C
VCCIO	VCCIO5	5			VCCIO5	5		
Y11	PB27A	5	BDQ24	T	PB36A	5	BDQ33	T
AB11	PB27B	5	BDQ24	C	PB36B	5	BDQ33	C
AE7	PB28A	5	BDQ24	T	PB37A	5	BDQ33	T
AF7	PB28B	5	BDQ24	C	PB37B	5	BDQ33	C
GND	GNDIO5	-			GNDIO5	-		
AC10	PB29A	5	BDQ33	T	PB38A	5	BDQ42	T
AD10	PB29B	5	BDQ33	C	PB38B	5	BDQ42	C
AA12	PB30A	5	BDQ33	T	PB39A	5	BDQ42	T
W12	PB30B	5	BDQ33	C	PB39B	5	BDQ42	C
AB12	PB31A	5	BDQ33	T	PB40A	5	BDQ42	T
VCCIO	VCCIO5	5			VCCIO5	5		
Y12	PB31B	5	BDQ33	C	PB40B	5	BDQ42	C
AD12	PB32A	5	BDQ33	T	PB41A	5	BDQ42	T
AC12	PB32B	5	BDQ33	C	PB41B	5	BDQ42	C
AC13	PB33A	5	BDQS33	T	PB42A	5	BDQS42	T
GND	GNDIO5	-			GNDIO5	-		
AA13	PB33B	5	BDQ33	C	PB42B	5	BDQ42	C
AD13	PB34A	5	BDQ33	T	PB43A	5	BDQ42	T
AC14	PB34B	5	BDQ33	C	PB43B	5	BDQ42	C
AE8	PB35A	5	BDQ33	T	PB44A	5	BDQ42	T
VCCIO	VCCIO5	5			VCCIO5	5		
AF8	PB35B	5	BDQ33	C	PB44B	5	BDQ42	C
AB15	PB36A	5	BDQ33	T	PB45A	5	BDQ42	T
Y13	PB36B	5	BDQ33	C	PB45B	5	BDQ42	C
AE9	PB37A	5	BDQ33	T	PB46A	5	BDQ42	T
GND	GNDIO5	-			GNDIO5	-		
AF9	PB37B	5	BDQ33	C	PB46B	5	BDQ42	C
W13	PB38A	5	BDQ42	T	PB47A	5	BDQ51	T

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AB24	PR87B	8	D3	C
GND	GNDIO4	-		
AB23	PR87A	8	D4	T
AB25	PR86B	8	D5	C
AB26	PR86A	8	D6	T
AC27	PR85B	8	D7/SPID0	C
VCCIO	VCCIO8	8		
AB27	PR85A	8	DI/CSSPI0N	T
AD29	PR84B	8	DOUT/CSON	C
AD30	PR84A	8	BUSY/SISPI	T
AA25	PR83B	3	RDQ80	C
GND	GNDIO3	-		
AA23	PR83A	3	RDQ80	T
AC29	PR82B	3	RDQ80	C (LVDS)*
AC30	PR82A	3	RDQ80	T (LVDS)*
AA26	PR81B	3	RDQ80	C
VCCIO	VCCIO3	3		
AA24	PR81A	3	RDQ80	T
AB29	PR80B	3	RDQ80	C (LVDS)*
AB30	PR80A	3	RDQS80	T (LVDS)*
GND	GNDIO3	-		
Y23	PR79B	3	RDQ80	C
Y25	PR79A	3	RDQ80	T
AA27	PR78B	3	RDQ80	C (LVDS)*
AA28	PR78A	3	RDQ80	T (LVDS)*
VCCIO	VCCIO3	3		
Y24	PR77B	3	RLM0_GPLLC_FB_A/RDQ80	C
Y26	PR77A	3	RLM0_GPLLT_FB_A/RDQ80	T
AA29	PR76B	3	RLM0_GPLLC_IN_A**/RDQ80	C (LVDS)*
AA30	PR76A	3	RLM0_GPLLT_IN_A**/RDQ80	T (LVDS)*
R22	RLM0_PLLCAP	3		
W23	PR74B	3	RLM0_GDLLC_FB_A/RDQ71	C
W25	PR74A	3	RLM0_GDLLT_FB_A/RDQ71	T
GND	GNDIO3	-		
Y27	PR73B	3	RLM0_GDLLC_IN_A**/RDQ71	C (LVDS)*
Y28	PR73A	3	RLM0_GDLLT_IN_A**/RDQ71	T (LVDS)*
W24	PR72B	3	RDQ71	C
W26	PR72A	3	RDQ71	T
VCCIO	VCCIO3	3		
Y29	PR71B	3	RDQ71	C (LVDS)*
Y30	PR71A	3	RDQS71	T (LVDS)*
V25	PR70B	3	RDQ71	C
GND	GNDIO3	-		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AG4	NC	-		
AG8	NC	-		
AH1	NC	-		
AH16	NC	-		
AH2	NC	-		
AH26	NC	-		
AH27	NC	-		
AH29	NC	-		
AH30	NC	-		
AH4	NC	-		
AJ1	NC	-		
AJ2	NC	-		
AJ27	NC	-		
AJ28	NC	-		
AJ29	NC	-		
AJ3	NC	-		
AJ30	NC	-		
AK2	NC	-		
AK27	NC	-		
AK28	NC	-		
AK29	NC	-		
AK3	NC	-		
B1	NC	-		
B2	NC	-		
B3	NC	-		
B30	NC	-		
B4	NC	-		
B5	NC	-		
C1	NC	-		
C2	NC	-		
C29	NC	-		
C30	NC	-		
C4	NC	-		
D13	NC	-		
D18	NC	-		
D23	NC	-		
D28	NC	-		
D29	NC	-		
D3	NC	-		
D30	NC	-		
D4	NC	-		
E25	NC	-		
E26	NC	-		

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
F15	NC	-			NC	-		
F14	NC	-			NC	-		
F13	NC	-			NC	-		
G12	NC	-			NC	-		
G13	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated sysCONFIG pins for the higher density devices (ECP2M50, ECP2M70 and ECP2M100).
****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
U12	PB59B	4	BDQ60	C
GNDIO	GNDIO4	-		
AA12	PB60A	4	BDQS60	T
Y12	PB60B	4	BDQ60	C
V12	PB61A	4	BDQ60	T
W12	PB61B	4	BDQ60	C
AB12	PB62A	4	BDQ60	T
AA13	PB62B	4	BDQ60	C
VCCIO	VCCIO4	4		
T12	PB63A	4	BDQ60	T
U13	PB63B	4	BDQ60	C
V13	PB64A	4	BDQ60	T
T13	PB64B	4	BDQ60	C
GNDIO	GNDIO4	-		
AB13	PB65A	4	BDQ69	T
AB14	PB65B	4	BDQ69	C
U14	PB66A	4	BDQ69	T
T14	PB66B	4	BDQ69	C
AA14	PB67A	4	BDQ69	T
VCCIO	VCCIO4	4		
Y14	PB67B	4	BDQ69	C
W14	PB68A	4	BDQ69	T
V14	PB68B	4	BDQ69	C
AB15	PB69A	4	BDQS69	T
GNDIO	GNDIO4	-		
AA15	PB69B	4	BDQ69	C
V15	PB70A	4	BDQ69	T
U15	PB70B	4	BDQ69	C
AB16	PB71A	4	BDQ69	T
VCCIO	VCCIO4	4		
AA16	PB71B	4	BDQ69	C
AB17	PB72A	4	BDQ69	T
AA17	PB72B	4	BDQ69	C
GNDIO	GNDIO4	-		
W20	CFG2	8		
V20	CFG1	8		
V19	CFG0	8		
V22	PROGRAMN	8		
W22	CCLK	8		
U18	INITN	8		
U22	DONE	8		
GNDIO	GNDIO8	-		
U20	WRITEN***	8		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
Y15	GND	-			GND	-		
Y16	GND	-			GND	-		
Y17	GND	-			GND	-		
AA26	NC	-			NC	-		
AB10	PL73B	6	LDQ71	C (LVDS)*	NC	-		
AB11	NC	-			NC	-		
AB12	NC	-			NC	-		
AB13	NC	-			NC	-		
AB14	NC	-			NC	-		
AB15	NC	-			NC	-		
AB16	NC	-			NC	-		
AB17	NC	-			NC	-		
AB19	NC	-			NC	-		
AB20	NC	-			NC	-		
AB21	NC	-			NC	-		
AB9	PL73A	6	LDQ71	T (LVDS)*	NC	-		
AC10	PL74B	6	LDQ71	C	NC	-		
AC11	NC	-			NC	-		
AC21	NC	-			NC	-		
AC22	NC	-			NC	-		
AC8	PL70B	6	LDQ71	C	NC	-		
AC9	PL74A	6	LDQ71	T	NC	-		
AD21	NC	-			NC	-		
AD22	NC	-			NC	-		
AD4	PL68A	6	LDQ71	T	NC	-		
AD5	PL68B	6	LDQ71	C	NC	-		
AD6	PL71A	6	LDQS71	T (LVDS)*	NC	-		
AD7	PL72A	6	LDQ71	T	NC	-		
AD8	PL72B	6	LDQ71	C	NC	-		
AE23	NC	-			NC	-		
AE5	PL69A	6	LDQ71	T (LVDS)*	NC	-		
AE6	PL70A	6	LDQ71	T	NC	-		
AE7	PL71B	6	LDQ71	C (LVDS)*	NC	-		
AF20	NC	-			NC	-		
AF23	NC	-			NC	-		
AF5	PL69B	6	LDQ71	C (LVDS)*	NC	-		
AG23	NC	-			NC	-		
AG26	NC	-			NC	-		
D10	PT10A	0		T	NC	-		
E10	PT9B	0		C	NC	-		
E11	PT10B	0		C	NC	-		
F10	PT9A	0		T	NC	-		
F20	NC	-			NC	-		
F23	NC	-			NC	-		
F8	PL6B	7	LDQ6	C (LVDS)*	NC	-		
G10	NC	-			NC	-		
G20	NC	-			NC	-		
G21	NC	-			NC	-		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
GNDIO	GNDIO2	-		
M27	PR47B	2	RDQ45	C (LVDS)*
M28	PR47A	2	RDQ45	T (LVDS)*
H30	PR46B	2	RDQ45	C
G30	PR46A	2	RDQ45	T
VCCIO	VCCIO2	2		
M25	PR45B	2	RDQ45	C (LVDS)*
M26	PR45A	2	RDQS45	T (LVDS)*
L30	PR44B	2	RDQ45	C
GNDIO	GNDIO2	-		
L29	PR44A	2	RDQ45	T
L28	PR43B	2	RDQ45	C (LVDS)*
L27	PR43A	2	RDQ45	T (LVDS)*
H29	PR42B	2	RDQ45	C
VCCIO	VCCIO2	2		
G29	PR42A	2	RDQ45	T
L22	PR41B	2	RDQ45	C (LVDS)*
M22	PR41A	2	RDQ45	T (LVDS)*
F30	PR40B	2		C
GNDIO	GNDIO2	-		
F29	PR40A	2		T
VCCIO	VCCIO2	2		
GNDIO	GNDIO2	-		
E30	PR34B	2	RDQ32	C (LVDS)*
E29	PR34A	2	RDQ32	T (LVDS)*
-	-	-		
L25	PR33B	2	RDQ32	C
L26	PR33A	2	RDQ32	T
VCCIO	VCCIO2	2		
H28	PR32B	2	RDQ32	C (LVDS)*
J28	PR32A	2	RDQS32	T (LVDS)*
G28	PR31B	2	RDQ32	C
GNDIO	GNDIO2	-		
G27	PR31A	2	RDQ32	T
L24	PR30B	2	RDQ32	C (LVDS)*
L23	PR30A	2	RDQ32	T (LVDS)*
D30	PR29B	2	RDQ32	C
VCCIO	VCCIO2	2		
D29	PR29A	2	RDQ32	T
K24	PR28B	2	RDQ32	C (LVDS)*
K25	PR28A	2	RDQ32	T (LVDS)*
J27	PR26B	2	RDQ23	C
GNDIO	GNDIO2	-		

Date	Version	Section	Change Summary
November 2009 (cont.)	03.5 (cont.)	Pinout Information (cont.)	LatticeECP2M Pin Information Summary, LFE2M50, LFE2M70 and LFE2M100 table - corrected values for LFE2M50, 672 fpBGA in Available DDR-Interfaces per I/O Bank.
			Minor corrections in LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA table.
			Minor corrections in LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA table.
			Minor corrections in LFE2M100E/SE Logic Signal Connections: 900 fpBGA table.
			Updated LFE2-6E/SE and LFE2-12E/SE Logical Signal Connections (changed D1/SPIDS to D1).
		Ordering Information	Updated LatticeECP2M Part Number Description diagram.
March 2010	03.6	DC and Switching Characteristics	Footnote for SED operating frequency added to the sysCONFIG Port Timing Specifications table.
		Pinout Information	Changed Dual Function pin E7 to be D7/SPDI0 in Logic Signal Connections tables. Changed footnote (***) in Logic Signal Connections table.
July 2010	03.7	Architecture	Updated the Typical sysIO Behavior During Power-up text section.
		Pinout Information	Added reference to powerup information.
			Corrected reference to footnote for pins 131 and 132 for the LFE-20E/SE, 208 PQFP.
			Referenced footnote (***) for all D7/SPID0.
			Changed D7*** to D7/SPID0.
			Corrected *** footnote.
		All Sections	Included references to Lattice Diamond design software wherever ispLEVER and ispLeverCORE is specified.
April 2011	03.8	DC and Switching Characteristics	DC Electrical Characteristics table: - Added footnote 3 to I_{IH} - Added footnote 2 to I_{IL}, I_{IH} - Updated C1 and C2 typ. and max. data.
			DLL Timing table – Removed line for t_R and t_F.
			LatticeECP2/M sysCONFIG Port Timing Specifications table – added footnote to t_{DINIT}.
			Figure 3-18 – Corrected label to be PRGM (not PRGMRJ).
		Pinout Information	LFE2-12E/SE and LFE-20/SE Logical Signal Connections for 208 PQFP – Corrected Dual Function information for pins 112, 114, 117, 119.
January 2012	03.9	Multiple	Removed references to ispLEVER design software.
		Architecture	Corrected information regarding SED support.
		DC and Switching Characteristics	Added reference to ESD information.
June 2013	04.0	All	Updated document with new corporate logo.
		Architecture	Architecture Overview – Added information on the state of the register on power up and after configuration.